

S/N 10/823,314

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Neo C. Peng et al.

Examiner: Samuel Heinrich

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Title: WAFER DICING DEVICE AND METHOD

RESPONSE UNDER 37 C.F.R. § 1.116 - EXPEDITED PROCEDURE

Mail Stop RCE

Commissioner for Patents

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This paper is responsive to the Advisory Action mailed November 19, 2008.